

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

1. (Canceled)
2. (Previously Presented) A manufacturing method according to claim 15, wherein the increasing comprises disposing a casing comprising at least one bottom half-shell at least under the contact pads.
3. (Previously Presented) A manufacturing method according to claim 2, further comprising interfitting the bottom half-shell with a top half-shell covering a zone of the microcircuit that lies outside the contact pads.
4. (Previously Presented) A manufacturing method according to claim 15, wherein the increasing comprises inserting the microcircuit into a shell having an access on a rear edge.
5. (Previously Presented) A manufacturing method according to claim 15, wherein the increasing comprises forming an overmolded portion over the microcircuit.

6. (Previously Presented) A manufacturing method according to claim 2, further comprising fastening the microcircuit to the bottom half-shell.

7. (Previously Presented) A manufacturing method according to claim 6, wherein the fastening is by adhesive bonding or by tight-fitting cross-wise at least.

8. (Previously Presented) A manufacturing method according to claim 15, wherein the electronic component is disposed at a location offset from a location of the contact pads.

9. (Previously Presented) A manufacturing method according to claim 15, wherein the electronic component is disposed on the same top face of the microcircuit as the contact pads.

10 - 14. (Canceled)

15. (Currently Amended) A method for manufacturing a USB electronic key, comprising cutting out, from a ~~tape having dielectric backing film which has a thickness of less than or equal to 200 µm and carries~~ a plurality of microcircuits, a portion of the ~~tape dielectric backing film~~ including one of the microcircuits, each microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads; and, in a single operation, increasing the thickness of the cut-out portion of the ~~tape dielectric backing film~~ including the one of the microcircuits at

least in the area of the contact pads of the one of the microcircuits, so as to have a thickness that conforms to the USB Standard.

16. (New) A method for manufacturing a USB electronic key from a dielectric backing film which has a thickness of less than or equal to 200  $\mu\text{m}$  and carries a microcircuit, the microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads, the method comprising, in a single operation, increasing the thickness of the dielectric backing film including the microcircuit at least in the area of the contact pads of the microcircuit, so as to have a thickness that conforms to the USB Standard.

17. (New) A manufacturing method according to claim 16, wherein the increasing comprises disposing a casing comprising at least one bottom half-shell at least under the contact pads.

18. (New) A manufacturing method according to claim 17, further comprising interfitting the bottom half-shell with a top half-shell covering a zone of the microcircuit that lies outside the contact pads.

19. (New) A manufacturing method according to claim 16, wherein the increasing comprises inserting the microcircuit into a shell having an access on a rear edge.

20. (New) A manufacturing method according to claim 16, wherein the increasing comprises forming an overmolded portion over the microcircuit.

21. (New) A manufacturing method according to claim 17, further comprising fastening the microcircuit to the bottom half-shell.

22. (New) A manufacturing method according to claim 21, wherein the fastening is by adhesive bonding or by tight-fitting cross-wise at least.

23. (New) A manufacturing method according to claim 16, wherein the electronic component is disposed at a location offset from a location of the contact pads.

24. (New) A manufacturing method according to claim 16, wherein the electronic component is disposed on the same top face of the microcircuit as the contact pads.